

IFW



INT-03-008

December 9, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |

Thomas Aisenbrey

LOW COST THERMAL MANAGEMENT DEVICE  
OR HEAT SINK USING CONDUCTIVE  
PLASTICS OR CONDUCTIVE COMPOSITES

#### SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner for Patents,  
P.O. Box 1450, Alexandria, VA 22313-1450, on December 13, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 12/13/04

U.S. Patent 5,857,767 to Hochstein, "Thermal Management System for L.E.D. Arrays," discloses a method of manufacturing an electrically driven L.E.D. lamp assembly.

U.S. Patent 6,364,009 to MacManus et al., "Cooling Devices," discloses a cooling apparatus for cooling an electrical device using a flow of coolant comprising a cooling unit.

U.S. Patent 5,849,130 to Browne, "Method of Making and Using Thermally Conductive Joining Film," discusses a thermally conductive film that includes a film of polymeric matrix material having a thickness defined between a top surface and a bottom surface.

European Patent Application EP 0 506 509 A to Sono et al., "Semiconductor Device Having Radiation Part and Method of Producing the Same," discloses a semiconductor device having a radiation part for radiating heat and a method of producing such a semiconductor device.

International Patent Application WO 03/017365 A to Flint et al., "Thermal Transfer Devices," discusses thermal transfer devices, including heat pipes and vapor chambers.

U.S. Patent 6,397,941 to McCullough, "Net-Shape Molded Heat Exchanger," discloses a net-shape molded heat exchanger which includes a thermally conductive main body and a number of thermally conductive arms connected to and extending from the main body.

European Patent Application EP 1 265 281 A to Tobita et al., "Thermally Conductive Molded Article and Method of Making the Same," discloses a thermally conductive molded article that has excellent thermal conductivity and a method of making the same.

International Patent Application WO 95/09444 to Moore, "LED Assembly with Enhanced Power Output," discloses a light emitting diode (LED) assembly which is designed for use in a remote control and which has enhanced power output.

U.S. Patent Application Publication US 2002/0178621 to Song et al., "Light Emitting Diode, Light Emitting Device Using the Same, and Fabrication Processes Therefor," discloses a LED which can be mounted at high density on a large area display.

U.S. Patent Application Publication US 2002/0072137 to Ih, "Optosemiconductor Device and the Method for Its Manufacture," discloses an optosemiconductor device, improved in light-emission efficiency and heat-radiation capability.

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U.S. Patent Application Publication US 2001/0050441 to Shivkumar et al., "Semiconductor Multichip Module Package with Improved Thermal Performance; Reduced Size and Improved Moisture Resistance," discloses a multichip module which has a substrate, which receives several flip chip and for other semiconductor die on one surface and has vias extending through the substrate from the flip chip bottom electrodes to solder ball electrodes on the bottom of the substrate.

U.S. Patent Application Publication US 2002/0109634 to Aisenbrey, "Low Cost Antennas Using Conductive Plastics or Conductive Composites," discusses low cost antennas formed of conductive loaded resin-based materials.

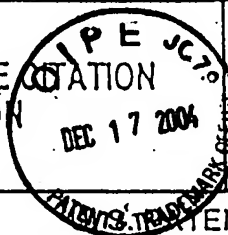
Sincerely,



Stephen B. Ackerman,  
Reg. No. 37761

# INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)



DocId Number (Optional)

INT-03-008

Application Number

10/807,036

Applicant

Thomas Aisenbrey

Filing Date

03/23/04

Group Art Unit

## PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5857767	1/12/99	Hochstein	362	294	2/25/97
	6364009	4/2/02	MacManus et al.	165	185	1/26/00
	5849130	12/15/98	Browne	156	256	6/12/97
	6397941	6/4/02	McCullough	165	185	11/7/00

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
	EP 0 50 6 50 9 A	23/16/92	European Patent App.	H01L	23/055		
	WO 03/01 736 5 A	28/17/01	Int'l Patent App.	H01L	23/34		
	EP 1 2 6 5 2 8 1 A	26/5/02	European Patent App.	H01L	23/373		
	WO 95 / 094 44 A	9/20/94	Int'l Patent App.	H01L	33/00		

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

-	US Patent App. Pub. US 2002/0175621 A1 to Song et al., Filed 10/19/01, Pub. Date 11/28/02, US Cl. 313/515.
-	US Patent App. Pub. US 2002/0072137 A1 to Jh, Filed 03/05/01, Pub. Date 06/13/02, US Cl. 438/22.
-	US Patent App. Pub. US 2001/0050441 A1 to Shivkumar et al., Filed 03/19/01, Pub. Date 12/13/01, US Cl. 257/778.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

